256Kx64 SRAM MODULE *ADVANCED**

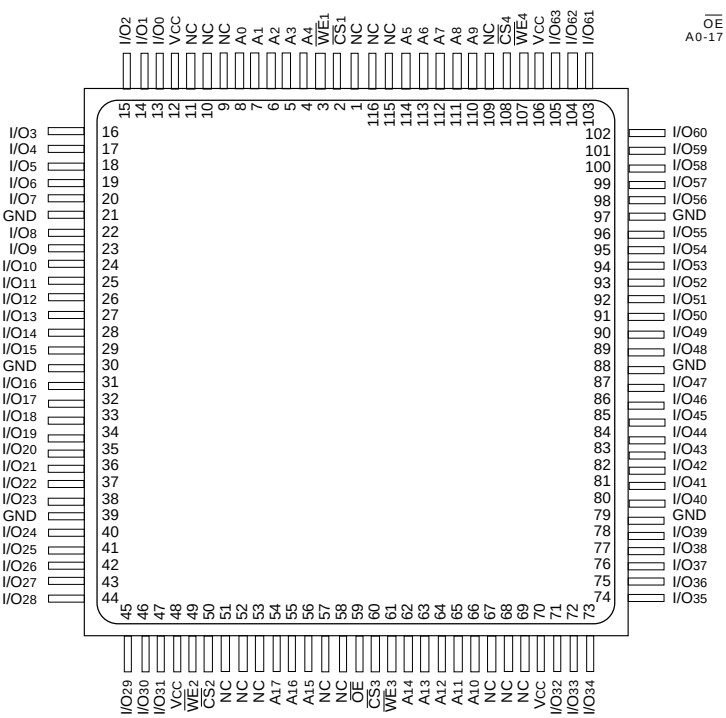
FEATURES

- Access Times 20, 25, 35ns
- MIL-STD-883 Compliant Devices Available
- Packaging:
  - 116 lead, 40mm, Hermetic CQFP (Package 504)
- Organized as 256Kx64, User Configurable as 512Kx32 or 1Mx16.
- Data I/O Compatible with 3.3V devices
- 2V Data Retention devices available
- Commercial, Industrial and Military Temperature Range
- 5 Volt Power Supply
- Low Power CMOS
- TTL Compatible Inputs and Outputs
- Weight
  WS256K64-XG4WX - 20 grams typical

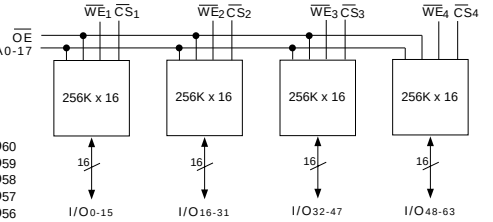
* *This data sheet describes a product that may or may not be under development and is subject to change or cancellation without notice.*

FIG. 1 PIN CONFIGURATION FOR WS256K64-XG4WX

TOP VIEW



BLOCK DIAGRAM



PIN DESCRIPTION

I/O0-63	Data Inputs/Outputs
A0-17	Address Inputs
$\overline{WE}_{1-4}$	Write Enables
$\overline{CS}_{1-4}$	Chip Selects
$\overline{OE}$	Output Enable
VCC	Power Supply
GND	Ground

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Min	Max	Unit
Operating Temperature	T_A	-55	+125	°C
Storage Temperature	T_{STG}	-65	+150	°C
Signal Voltage Relative to GND	V_G	-0.5	V_{CC} + 0.5	V
Junction Temperature	T_J		150	°C
Supply Voltage	V_{CC}	-0.5	7.0	V

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Min	Max	Unit
Supply Voltage	V_{CC}	4.5	5.5	V
Input High Voltage	V_{IH}	2.2	V_{CC} + 0.3	V
Input Low Voltage	V_{IL}	-0.3	+0.8	V
Operating Temp. (Mil.)	T_A	-55	+125	°C

TRUTH TABLE

$\overline{CS}$	$\overline{OE}$	$\overline{WE}$	Mode	Data I/O	Power
H	X	X	Standby	High Z	Standby
L	L	H	Read	Data Out	Active
L	X	L	Write	Data In	Active
L	H	H	Out Disable	High Z	Active

CAPACITANCE

(T_A = +25°C)

Parameter	Symbol	Condition	Max	Unit
Output Enable Capacitance	C_{OE}	V_{IN} = 0V, f = 1.0MHz	50	pF
Write Enable Capacitance	C_{WE}	V_{IN} = 0V, f = 1.0MHz	20	pF
Chip Select Capacitance	C_{CS}	V_{IN} = 0V, f = 1.0MHz	20	pF
Data I/OCapacitance	$C_{I/O}$	V_{IN} = 0V, f = 1.0MHz	20	pF
Address Input Capacitance	C_{AD}	V_{IN} = 0V, f = 1.0MHz	50	pF

This parameter is guaranteed by design but not tested.

DC CHARACTERISTICS

(V_{CC} = 5.0V, GND = 0V, T_A = -55°C to +125°C)

Parameter	Sym	Conditions	Min	Max	Units
Input Leakage Current	I_{LI}	V_{CC} = 5.5, V_{IN} = GND to V_{CC}		10	µA
Output Leakage Current	I_{LO}	$\overline{CS}$ = V_{IH}, $\overline{OE}$ = V_{IH}, V_{OUT} = GND to V_{CC}		10	µA
Operating Supply Current	I_{CC}	$\overline{CS}$ = V_{IL}, $\overline{OE}$ = V_{IH}, f = 5MHz, V_{CC} = 5.5		920	mA
Standby Current	I_{SB}	$\overline{CS}$ = V_{IH}, $\overline{OE}$ = V_{IH}, f = 5MHz, V_{CC} = 5.5		68	mA
Output Low Voltage	V_{OL}	I_{OL} = 8mA, V_{CC} = 4.5		0.4	V
Output High Voltage	V_{OH}	I_{OH} = -4.0mA, V_{CC} = 4.5	2.4		V

NOTE: DC test conditions: V_{IH} = V_{CC} -0.3V, V_{IL} = 0.3V

AC CHARACTERISTICS

(V_{CC} = 5.0V, GND = 0V, T_A = -55°C to +125°C)

Parameter	Symbol	-20		-25		-35		Units
Read Cycle		**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	
Read Cycle Time	t_{RC}	20		25		35		ns
Address Access Time	t_{AA}		20		25		35	ns
Output Hold from Address Change	t_{OH}	0		0		0		ns
Chip Select Access Time	t_{ACS}		20		25		35	ns
Output Enable to Output Valid	t_{OE}		12		15		20	ns
Chip Select to Output in Low Z	t_{CLZ}[1]	5		5		5		ns
Output Enable to Output in Low Z	t_{OLZ}[1]	0		0		0		ns
Chip Disable to Output in High Z	t_{CHZ}[1]		12		15		15	ns
Output Disable to Output in High Z	t_{OHZ}[1]		12		15		15	ns

1. This parameter is guaranteed by design but not tested.

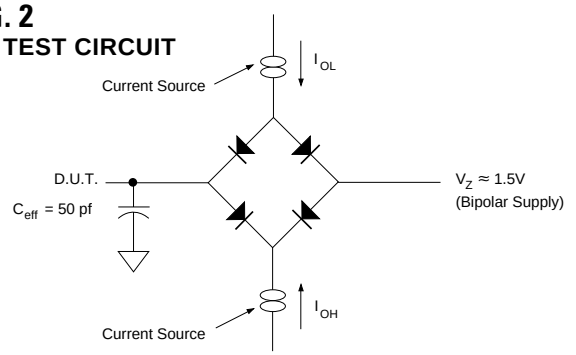
AC CHARACTERISTICS

(V_{CC} = 5.0V, GND = 0V, T_A = -55°C to +125°C)

Parameter	Symbol	-20		-25		-35		Units
Write Cycle		**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	
Write Cycle Time	t_{WC}	20		25		35		ns
Chip Select to End of Write	t_{CW}	17		20		25		ns
Address Valid to End of Write	t_{AW}	17		20		25		ns
Data Valid to End of Write	t_{DW}	12		15		20		ns
Write Pulse Width	t_{WP}	17		20		25		ns
Address Setup Time	t_{AS}	0		0		0		ns
Address Hold Time	t_{AH}	2		2		2		ns
Output Active from End of Write	t_{OW}[1]	0		0		0		ns
Write Enable to Output in High Z	t_{WHZ}[1]		10		10		15	ns
Data Hold Time	t_{DH}	0		0		0		ns

1. This parameter is guaranteed by design but not tested.

FIG. 2
AC TEST CIRCUIT

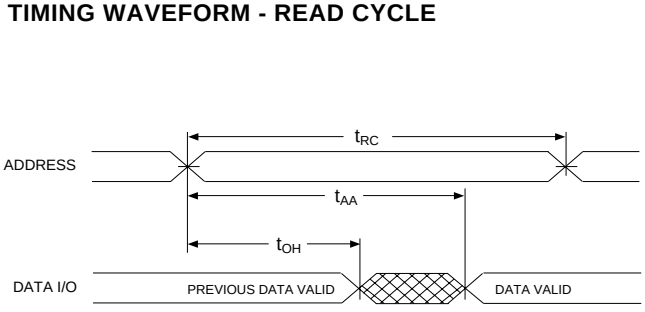


AC TEST CONDITIONS

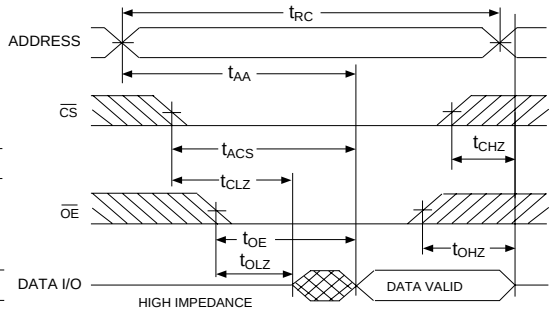
Parameter	Typ	Unit
Input Pulse Levels	V_{IL} = 0, V_{IH} = 3.0	V
Input Rise and Fall	5	ns
Input and Output Reference Level	1.5	V
Output Timing Reference Level	1.5	V

NOTES:
V_Z is programmable from -2V to +7V.
I_{OL} & I_{OH} programmable from 0 to 16mA.
Tester Impedance Z_0 = 75 Ω.
V_Z is typically the midpoint of V_{OH} and V_{OL}.
I_{OL} & I_{OH} are adjusted to simulate a typical resistive load circuit.
ATE tester includes jig capacitance.

FIG. 3
TIMING WAVEFORM - READ CYCLE

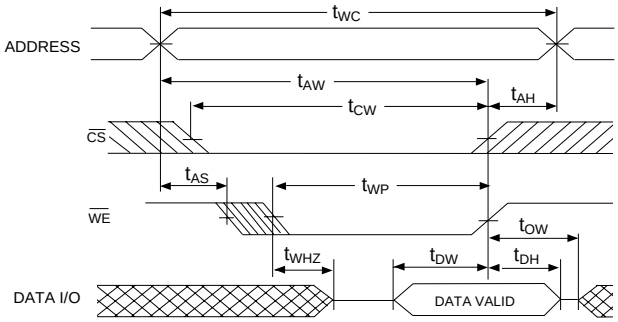


READ CYCLE 1 ($\overline{CS}$ = $\overline{OE}$ = V_{IL}, $\overline{WE}$ = V_{IH})



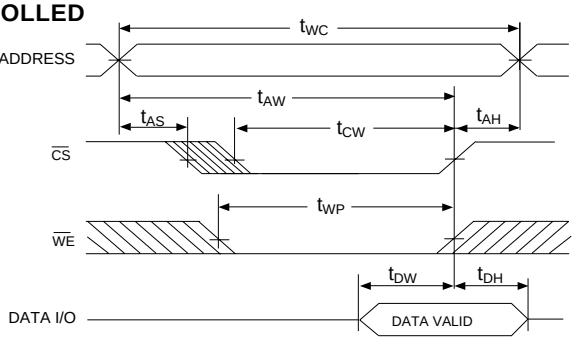
READ CYCLE 2 ($\overline{WE}$ = V_{IH})

FIG. 4
WRITE CYCLE - $\overline{WE}$ CONTROLLED



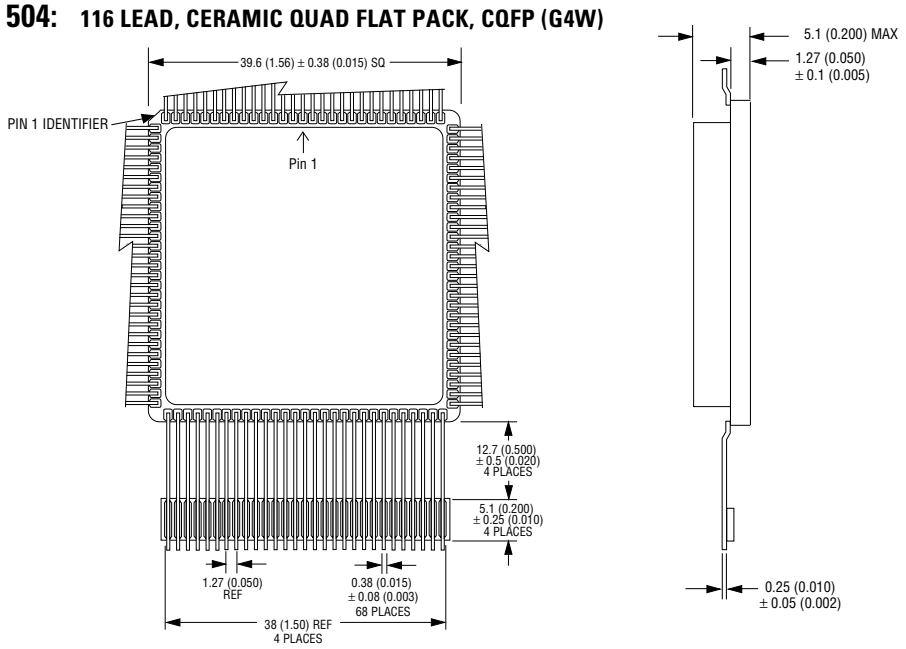
WRITE CYCLE 1, $\overline{WE}$ CONTROLLED

FIG. 5
WRITE CYCLE - $\overline{CS}$ CONTROLLED



WRITE CYCLE 2, $\overline{CS}$ CONTROLLED

PACKAGE 504: 116 LEAD, CERAMIC QUAD FLAT PACK, CQFP (G4W)



ALL LINEAR DIMENSIONS ARE MILLIMETERS AND PARENTHETICALLY IN INCHES

ORDERING INFORMATION

W S 256K64 - XXX G4W X

DEVICE GRADE:

M	= Military Screened	-55°C to +125°C
I	= Industrial	-40°C to +85°C
C	= Commercial	0°C to +70°C

PACKAGE:

G4W = 116 Lead 40mm Ceramic Quad Flat Pack, CQFP (Package 504)

ACCESS TIME (ns)

ORGANIZATION, 256K x 64

User configurable as 1M x 16 or 512K x 32

SRAM

WHITE MICROELECTRONICS